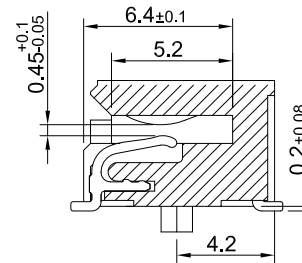
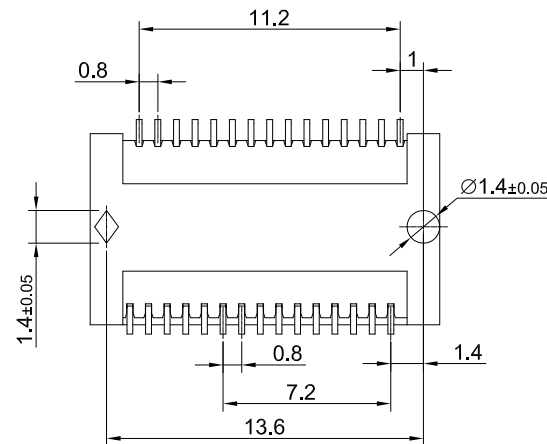
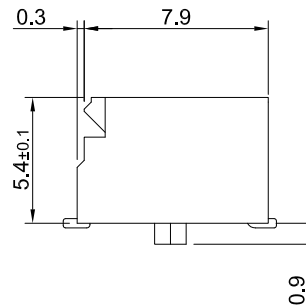
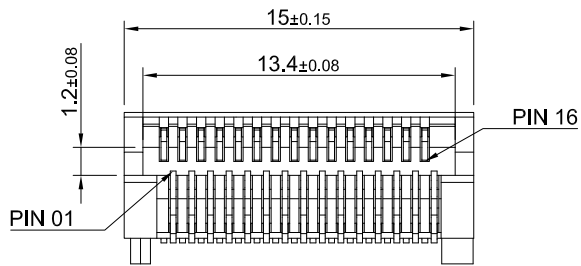


MATERIAL
 CONTACTS: COPPER ALLOY
 INSULATOR: LCP THERMOPLASTIC 94V-0

FINISH
 CONTACT: 15 μ" MIN. GOLD ON MATING END;
 MATTE TIN ON TERMINATION END;
 ALL UNDERPLATED NICKEL

ELECTRICAL CHARACTERISTICS
 CONTACT RESISTANCE: 35 MILLOHMS MAX.
 DIELECTRIC WITHSTANDING VOLTAGE: 300 VAC

ENVIRONMENT
 OPERATION TEMPERATURE: -55°C TO +85°C

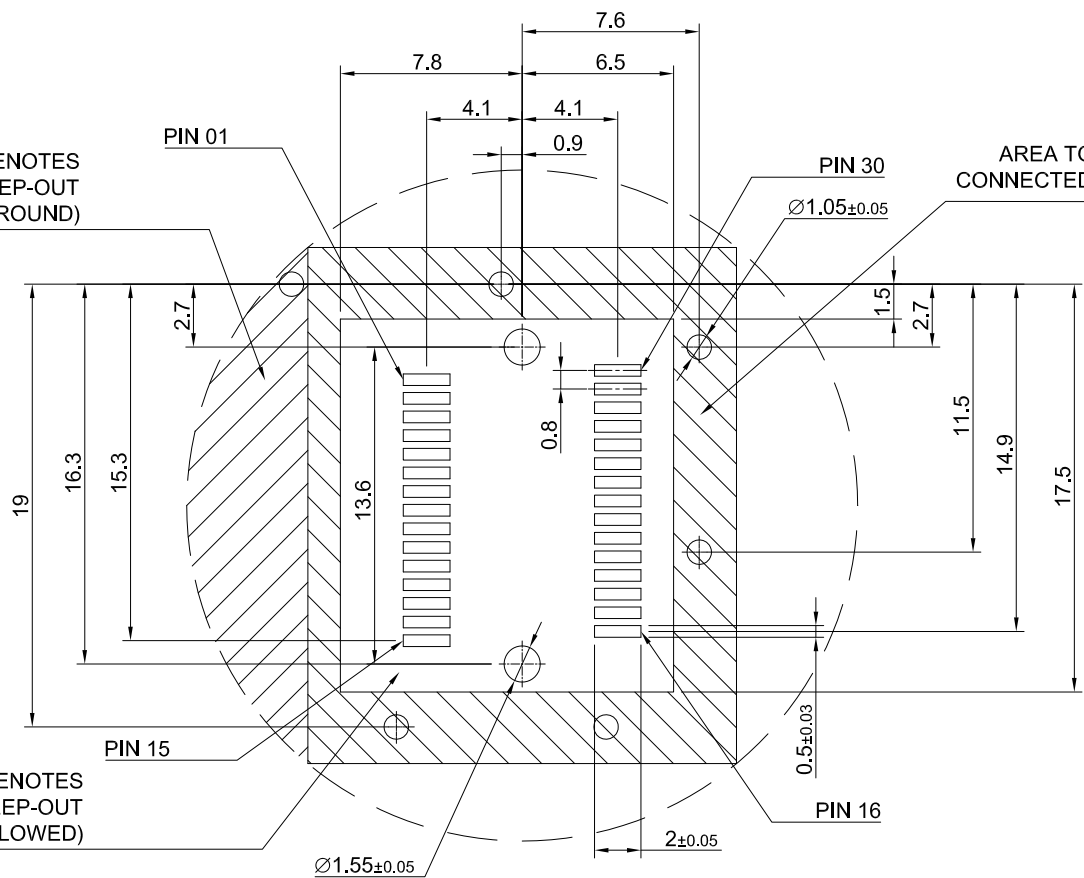


TITLE: XFP 30Pin PCB Connector			
DWG#: R-SS-008030-3-N		SHEET: 1/2	REV.: E
UNIT: mm	SCALE: A4 3:1	FINISH: RoHS Compliant	CHECKED: Gary Kang
TOLERANCE: Angle: ± 1° X, ± 0.25 .X ± 0.20 .XX ± 0.15		MATERIAL: RoHS Compliant	APPROVED: George Yang
		DRAWN: Sheng	DATE: 09/10/2014

CROSS HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

AREA TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND

THIS AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)



30 CIRCUIT MOTHER BOARD
RECOMMENED PCB LAYOUT
TOLERANCE:±0.05



TITLE: XFP 30Pin PCB Connector			
DWG#: R-SS-008030-3-N		SHEET: 2/2	REV. E
UNIT: mm	SCALE: A4 3:1	FINISH:	CHECKED: Gary Kang
THIRD ANGLE PROJECTION		MATERIAL: RoHS Compliant	APPROVED: George Yang
TOLERANCE: X,± 0.15 .XX± 0.05		DRAWN: Sheng	DATE: 09/10/2014